

TSMC 00-563

Application no. 09/863,224

#10/A 2823
2/20/03
Mullish

January 15, 2003



TO: Commissioner of Patents and Trademarks
Washington, D.C. 20231

FROM: Stephen Ackerman Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

SUBJECT: Serial # 09/863,224 ✓ File Date: 05/24/2001 ✓
Inventor: Ming-Hsing Tsai
Examiner: Neal Berezny
Art Unit: 2823
Title: A Method To Solve Via Poisoning For Porous Low-K Dielectric

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TC 2800 MAIL ROOM

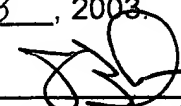
RESPONSE TO OFFICE ACTION

This is in response to the Final Office Action dated 11/01/02 Please amend the above identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to :
Commissioner of Patents and Trademarks, Washington, D.C. 20231 on

February 3, 2003.

Signature  Date: February 3, 2003
Stephen B. Ackerman, Reg. No. 37,761